

Title (en)

SELF-SUPPORTING CONTACTING STRUCTURES THAT ARE DIRECTLY PRODUCED ON COMPONENTS WITHOUT HOUSINGS

Title (de)

DIREKT AUF UNGEHÄUSTEN BAUELEMENTEN ERZEUGTE FREITRAGENDE KONTAKTIERSTRUKTUREN

Title (fr)

STRUCTURES DE MISE EN CONTACT AUTOPORTANTES PRODUITES DIRECTEMENT SUR DES COMPOSANTS SANS BOITIER

Publication

EP 1597755 A2 20051123 (DE)

Application

EP 04702322 A 20040115

Priority

- EP 2004000263 W 20040115
- DE 10308928 A 20030228

Abstract (en)

[origin: WO2004077546A2] A self-supporting contacting structure is directly produced on a component that does not have a housing by applying a layer made of nonconducting material and a layer made of an electrically conductive material to the component and to a support and by subsequently removing these layers from said support.

IPC 1-7

H01L 21/60; **H01L 21/68**

IPC 8 full level

H01L 21/60 (2006.01); **H01L 21/56** (2006.01); **H01L 21/68** (2006.01); **H01L 23/48** (2006.01); **H01L 23/482** (2006.01)

CPC (source: EP KR US)

H01L 21/568 (2013.01 - EP US); **H01L 21/6835** (2013.01 - EP US); **H01L 23/4822** (2013.01 - EP US); **H01L 23/52** (2013.01 - KR); **H01L 24/19** (2013.01 - EP US); **H01L 24/24** (2013.01 - EP US); **H01L 24/82** (2013.01 - EP US); **H01L 2224/2402** (2013.01 - EP US); **H01L 2224/24051** (2013.01 - EP US); **H01L 2224/24226** (2013.01 - EP US); **H01L 2224/24227** (2013.01 - EP US); **H01L 2224/82001** (2013.01 - EP US); **H01L 2924/01004** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01015** (2013.01 - EP US); **H01L 2924/0102** (2013.01 - EP US); **H01L 2924/01027** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01047** (2013.01 - EP US); **H01L 2924/01051** (2013.01 - EP US); **H01L 2924/01061** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01074** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/15153** (2013.01 - EP US); **H01L 2924/15165** (2013.01 - EP US); **H01L 2924/19043** (2013.01 - EP US); **H01L 2924/30107** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US); **Y10T 29/4913** (2015.01 - EP US); **Y10T 29/49144** (2015.01 - EP US); **Y10T 29/49149** (2015.01 - EP US)

Citation (search report)

See references of WO 2004077546A2

Designated contracting state (EPC)

DE FR IE

DOCDB simple family (publication)

DE 10308928 A1 20040909; **DE 10308928 B4 20090618**; CN 1754255 A 20060329; EP 1597755 A2 20051123; JP 2006519475 A 20060824; KR 20050106467 A 20051109; US 2006248716 A1 20061109; US 7368324 B2 20080506; WO 2004077546 A2 20040910; WO 2004077546 A3 20050519

DOCDB simple family (application)

DE 10308928 A 20030228; CN 200480005210 A 20040115; EP 04702322 A 20040115; EP 2004000263 W 20040115; JP 2005518520 A 20040115; KR 20057016079 A 20050827; US 54717405 A 20050826